

REMARKS

In view of the above amendments and following remarks, reconsideration and further examination are requested.

By the current Amendment, claims 15, 19, 20, 23-25, 28 and 30 have been amended.

In the Final Rejection mailed April 28, 2004, claims 15-30 were rejected under 35 U.S.C. § 103(a) as being unpatentable of Li et al. in view of Omoya et al. A combination of Li et al. and Omoya et al. is not believed to be applicable with regard to the currently amended claims for the following reasons.

Each of the independent claims 15, 19 and 23 have been amended to recite that the conductive adhesive includes **thermoplastic resins or thermosetting resins**. It is respectfully submitted that one having ordinary skill in the art would not have found it obvious to modify Li et al. by substituting a conductive adhesive including thermoplastic resins or thermosetting resins for the material of conductive posts 45 and 47 of Li et al., because to do so would have deteriorated the wiring substrate of Li et al.

In this regard, in forming the substrate of Li et al., a photo-resist layer 51 is formed on base substrate 27 as shown in Figure 3A, then posts 45 and 47 are formed as shown in Figure 3B, then the photo-resist layer 51 is removed as shown in Figure 4, then insulating layer 54 is formed on the base substrate 27 and posts 45 and 47 as shown in Figure 5, and then holes 57 and 59 are formed in the insulating layer 54 to expose the posts 45 and 47 as shown in Figure 6A. Thus, two removal operations are performed after the posts 45 and 47 have been formed; namely, removal of the photo-resist layer 51 and removal of portions of insulating layer 54 to provide holes 57 and 59. Accordingly, were the conductive posts 45 and 47 to be formed from a conductive adhesive including thermoplastic resins or thermosetting resins, then at least a portion of these posts would also be removed during etching performed for the aforementioned two removal operations.

Thus, one having ordinary skill in the art would not have been motivated to modify Li. et al. in view of Omoya et al. by substituting conductive adhesive as taught by Omoya et al. for the material of conductive posts 45 and 47 of Li et al., because to do so would result in these conductive posts at least being partly removed or deteriorated during removal of the photo-resist layer 51 and/or

portions of insulating layer 54 corresponding to holes 57 and 59, so as to deteriorate the wiring substrate of Li et al.

In view of the above, it is respectfully submitted that one having ordinary skill in the art would not have sought to combine Li et al. and Omoya et al. for the reasons as presented by the Examiner. Thus, claims 15-30 are allowable over a combination of Li. et al. and Omoya et al.

Additionally, independent claims 15 and 19 recite that the resin film has the conductive adhesive portions on a surface of the resin film. This is shown in Figures 4C - 4D (claim 15) and Figures 6A - 7B (claim 19), for example. Similarly, independent claim 23 recites that a resin film having conductive portions is used to form the package structure. In Li et al., the conductive posts 45 and 47 are formed prior to formation of the insulating layer 54, and thus are not on a surface of the insulating layer or resin film. Omoya et al. does not resolve this deficiency of Li et al. Thus, for this additional reason claims 15, 19 and 23 are each allowable over a combination of Li et al. and Omoya et al.

With regard to independent claim 19, this claim also recites that the resin film is initially separate from the main body. This is shown in Figure 6C or 7A, for example. Similarly, the package structure as recited in claim 23 is formed from a resin film that is initially separate from a main body. In Li et al., the insulating layer 54 is never separate from the base substrate or main body 27, and Omoya et al. does not resolve this deficiency of Li et al. Thus, for this additional reason claims 19 and 23 are each allowable over a combination of Li et al. and Omoya et al.

It is appreciated that in the final paragraph on page 3 of the Office Action the Examiner states that the resin film is initially separate from the main body, and directs Applicants' attention to Figure 8 of Li et al. However, it is not seen how Figure 8, nor any other figure of Li et al., shows a resin film that is initially separate from a main body. If the Examiner maintains this position, then he is respectfully requested to specifically explain how Li et al. teaches a resin film that is initially separate from a main body.

And, independent claim 19 also requires an elastomer layer on the resin film. This elastomer layer is shown as "9" in Figures 6C and 7A, for example. Such an elastomer layer is not taught or suggested by either of Li et al. and Omoya et al., and accordingly, for this additional reason claim 19 is allowable over a combination of these references.

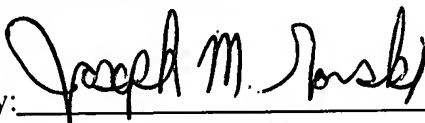
It is appreciated that in the final paragraph on page 3 and the initial paragraph on page 4 of the Office Action the Examiner expresses that the wiring substrate of Li et al. includes an elastomer layer on a resin film. However, it is not seen how Li et al. shows or suggests such an elastomer layer, and accordingly, if the Examiner maintains this position then he is respectfully requested to specifically explain how Li et al. teaches an elastomer layer on a resin film.

In view of the above amendments and remarks, it is respectfully submitted that the present application is in condition for allowance and an early Notice of Allowance is earnestly solicited.

If after reviewing this Amendment, the Examiner believes that any issues remain which must be resolved before the application can be passed to issue, the Examiner is invited to contact the Applicants' undersigned representative by telephone to resolve such issues.

Respectfully submitted,

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